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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

-·XEI

Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	40MHz
Connectivity	I ² C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	53
Program Memory Size	32KB (32K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-VFQFN Exposed Pad
Supplier Device Package	64-VQFN (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx420f032h-40i-mr

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Pin Diagrams (Continued)

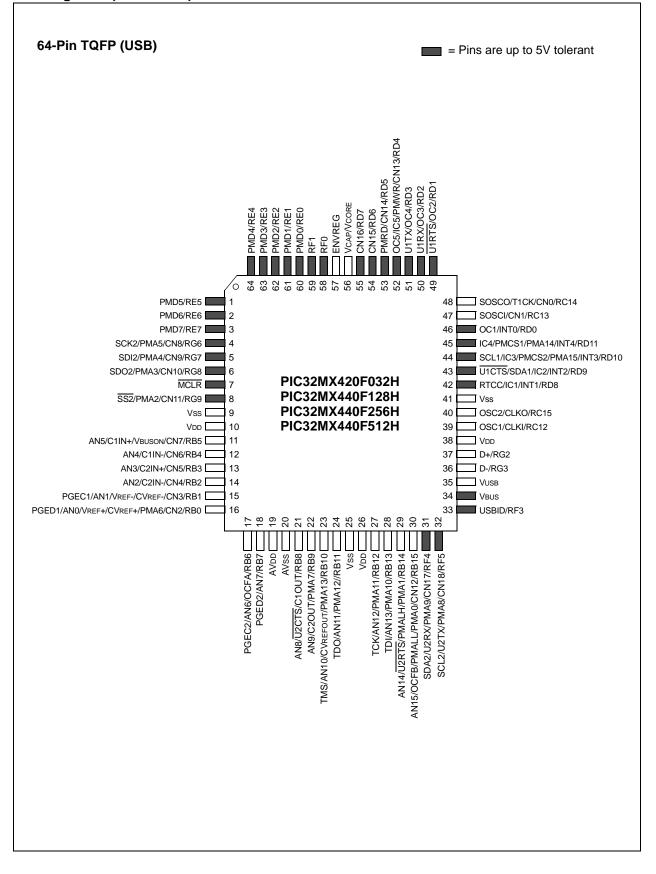
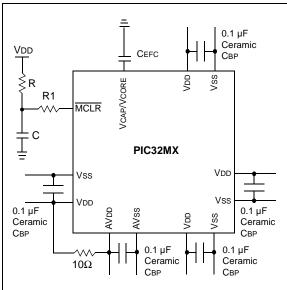


FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



2.2.1 BULK CAPACITORS

The use of a bulk capacitor is recommended to improve power supply stability. Typical values range from 4.7 μF to 47 μF . This capacitor should be located as close to the device as possible.

2.3 Capacitor on Internal Voltage Regulator (VCAP/VCORE)

2.3.1 INTERNAL REGULATOR MODE

A low-ESR (< 1 Ohm) capacitor is required on the VCAP/VCORE pin, which is used to stabilize the internal voltage regulator output. The VCAP/VCORE pin must not be connected to VDD, and must have a CEFC capacitor, with at least a 6V rating, connected to ground. The type can be ceramic or tantalum. Refer to **Section 29.0** "**Electrical Characteristics**" for additional information on CEFC specifications. This mode is enabled by connecting the ENVREG pin to VDD.

2.3.2 EXTERNAL REGULATOR MODE

In this mode the core voltage is supplied externally through the VCORE/VCAP pin. A low-ESR capacitor of 10 μF is recommended on the VCAP/VCORE pin. This mode is enabled by grounding the ENVREG pin.

The placement of this capacitor should be close to the VCAP/VCORE. It is recommended that the trace length not exceed one-quarter inch (6 mm). Refer to **Section 26.3** "**On-Chip Voltage Regulator**" for details.

2.4 Master Clear (MCLR) Pin

The MCLR pin provides for two specific device functions:

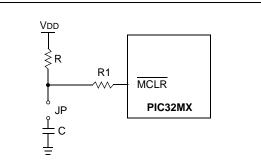
- Device Reset
- Device Programming and Debugging

Pulling The MCLR pin low generates a device reset. Figure 2-2 illustrates a typical MCLR circuit. During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the MCLR pin. Consequently, specific voltage levels (VIH and VIL) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as illustrated in Figure 2-2, it is recommended that the capacitor C, be isolated from the MCLR pin during programming and debugging operations.

Place the components shown in Figure 2-2 within one-quarter inch (6 mm) from the MCLR pin.

FIGURE 2-2:	EXAMPLE OF MCLR PIN
	CONNECTIONS



- Note 1: R ≤10 kΩ is recommended. A suggested starting value is 10 kΩ Ensure that the MCLR pin VIH and VIL specifications are met.
 - 2: $\underline{R1} \leq 470\Omega$ will limit any current flowing into MCLR from the external capacitor C, in the event of MCLR pin breakdown, due to Electrostatic Discharge (ESD) or <u>Electrical</u> Overstress (EOS). Ensure that the MCLR pin VIH and VIL specifications are met.
 - **3:** The capacitor can be sized to prevent unintentional resets from brief glitches or to extend the device reset period during POR.

SSS										В	its								
Virtual Address (BF88_#)	Register Name	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
	INTCON	31:16	_	—	_	_	_	_	—	_	_	—	_	—	—	—	_	SS0	00
1000	INTCON	15:0		—	—	MVEC	—		TPC<2:0>	•	—	—		INT4EP	INT3EP	INT2EP	INT1EP	INT0EP	00
1010	INTSTAT ⁽²⁾	31:16		_	-	_	_	_		—	_	_		_	_	_	_	_	00
1010	INTSTAT	15:0	-	—	—	_	—		SRIPL<2:0>	`	—	—			VEC	<5:0>			00
1020	IPTMR	31:16 15:0								IPTMF	<31:0>								00
	1500	31:16	I2C1MIF	I2C1SIF	I2C1BIF	U1TXIF	U1RXIF	U1EIF	_	_	—	OC5IF	IC5IF	T5IF	INT4IF	OC4IF	IC4IF	T4IF	00
1030	IFS0	15:0	INT3IF	OC3IF	IC3IF	T3IF	INT2IF	OC2IF	IC2IF	T2IF	INT1IF	OC1IF	IC1IF	T1IF	INT0IF	CS1IF	CS0IF	CTIF	00
1010	IFS1	31:16	_	—	_	_	_		USBIF	FCEIF	_	_	_	—	DMA3IF	DMA2IF	DMA1IF	DMA0IF	00
1040	IF51	15:0	RTCCIF	FSCMIF	I2C2MIF	I2C2SIF	I2C2BIF	U2TXIF	U2RXIF	U2EIF	SPI2RXIF	SPI2TXIF	SPI2EIF	CMP2IF	CMP1IF	PMPIF	AD1IF	CNIF	00
1060	IEC0	31:16	I2C1MIE	I2C1SIE	I2C1BIE	U1TXIE	U1RXIE	U1EIE	—	-	—	OC5IE	IC5IE	T5IE	INT4IE	OC4IE	IC4IE	T4IE	00
1060	IECU	15:0	INT3IE	OC3IE	IC3IE	T3IE	INT2IE	OC2IE	IC2IE	T2IE	INT1IE	OC1IE	IC1IE	T1IE	INT0IE	CS1IE	CS0IE	CTIE	00
1070		31:16		—	_	—	—		USBIE	FCEIE	—	_		—	DMA3IE	DMA2IE	DMA1IE	DMA0IE	00
1070	IEC1	15:0	RTCCIE	FSCMIE	I2C2MIE	I2C2SIE	I2C2BIE	U2TXIE	U2RXIE	U2EIE	SPI2RXIE	SPI2TXIE	SPI2EIE	CMP2IE	CMP1IE	PMPIE	AD1IE	CNIE	00
1090	IPC0	31:16	_	_	_		NT0IP<2:0>		INTOIS	S<1:0>	—	_	_		CS1IP<2:0>		CS1IS	<1:0>	00
1090	IPCU	15:0	—	—	—		CS0IP<2:0>		CSOIS	S<1:0>	—	—	—		CTIP<2:0>		CTIS	<1:0>	00
10A0	IPC1	31:16	_	-	-		NT1IP<2:0>		INT1IS	S<1:0>	—	_	_		OC1IP<2:0>	•	OC1IS	5<1:0>	00
IUAU	1 01	15:0		_	_		IC1IP<2:0>		IC1IS	5<1:0>	_	_			T1IP<2:0>		T1IS-	<1:0>	00
10B0	IPC2	31:16		_	_		NT2IP<2:0>		INT2IS	S<1:0>	—	_			OC2IP<2:0>		OC2IS	5<1:0>	00
IODO	11 02	15:0	_		—		IC2IP<2:0>		IC2IS	6<1:0>	—	—	_		T2IP<2:0>		T2IS-	<1:0>	00
10C0	IPC3	31:16	—	—	_		NT3IP<2:0>		INT3IS	S<1:0>	—	—	—		OC3IP<2:0>		OC3IS	5<1:0>	00
1000		15:0	_	_	_		IC3IP<2:0>			5<1:0>	—	—	_		T3IP<2:0>		T3IS-		00
10D0	IPC4	31:16	_	_	_		NT4IP<2:0>		INT4I	S<1:0>	—	—	_		OC4IP<2:0>	•	OC4IS	5<1:0>	00
		15:0	-	—	—		IC4IP<2:0>		IC4IS	5<1:0>	—	—	-		T4IP<2:0>		T4IS-		00
10E0	IPC5	31:16	_	_	_	—	—	—	—	—	—	—	_		OC5IP<2:0>		OC5IS	-	00
		15:0	—	—	—		IC5IP<2:0>			5<1:0>	—	—	_		T5IP<2:0>		T5IS-	-	00
10F0	IPC6	31:16	_	_	_		AD1IP<2:0>			S<1:0>	_	—	_		CNIP<2:0>		CNIS		00
		15:0	_	—	—		I2C1IP<2:0>			S<1:0>	_	—	_		U1IP<2:0>		U1IS-	-	00
1100	IPC7	31:16	_	—	—		SPI2IP<2:0>		-	S<1:0>	_	—	_		CMP2IP<2:0		CMP2I		00
		15:0	_	—	—		CMP1IP<2:0:			S<1:0>	_	—	_		PMPIP<2:0>		PMPIS		00
1110	IPC8	31:16	_	_	_		RTCCIP<2:0:			S<1:0>	_	—	_	F	SCMIP<2:0	>	FSCMI		00
		15:0	_	_	_		12C2IP<2:0>			S<1:0>	-	_	_		U2IP<2:0>		U2IS-		00
1120	IPC9	31:16	_	—	—		MA3IP<2:0:		-	S<1:0>	—	—	_		DMA2IP<2:0		DMA2I		00
		15:0	-	_	_		0MA1IP<2:0:	>	DMA1	S<1:0>	-	_	-	[DMA0IP<2:0		DMA0I	5<1:0>	00
	IPC11	31:16		_	_													_	00

Except where noted, all registers in this table have corresponding CLR, SET, and INV registers at their virtual addresses, plus offsets of 0x4, 0x8, and 0xC, respectively. See Section 12.1.1 "CLR, SET and INV Registers" for more information. Note 1:

This register does not have associated CLR, SET, and INV registers. 2:

TABLE 4-12: SPI1-2 REGISTERS MAP^(1,2)

e	ø																	
e e									В	ts								
Register Name	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
	31:16	FRMEN	FRMSYNC	FRMPOL	_	—	-		-	_	—	—	_			SPIFE	—	0000
FILCON	15:0	ON	—	SIDL	DISSDO	MODE32	MODE16	SMP	CKE	SSEN	CKP	MSTEN	—		—	—	—	0000
DIACTAT	31:16	—	—	—		—	_	_		—	—	—	—		_	—	—	0000
PIISIAI	15:0	—	—	_	_	SPIBUSY	_	_	_	—	SPIROV	_	_	SPITBE	_	_	SPIRBF	0008
	31:16								DATA	-04-0								0000
PIIDUF	15:0								DATA	31.0>								0000
	31:16	—	—	—	_	_	_	—	_	—	—	_	_		_	—		0000
FIIBRG	15:0		—	_	—	—	—	—					BRG<8:0>					0000
	31:16	FRMEN	FRMSYNC	FRMPOL		—	_		_	—	—	—	—	—	—	SPIFE		0008
PIZCON	15:0	ON	—	SIDL	DISSDO	MODE32	MODE16	SMP	CKE	SSEN	CKP	MSTEN	—	—	—	—	—	0000
	31:16		—	_	_	_	_	—	_	_	—	-	_	—	_	_	_	0000
FIZSIAI	15:0		—	_	_	SPIBUSY	_	-	_	-	SPIROV		_	SPITBE	_	-	SPIRBF	0008
	31:16									21:05								0000
	15:0								DATA	~01.0~								0000
	31:16	_	—	—	—	—	—	—	—	_	—	—	_	—	—	—		0000
DF IZDRG	15:0	_	_	_	_	_							BRG<8:0>					0000
SI F	PI1CON PI1STAT PI1BUF PI1BRG PI2CON PI2STAT PI2BUF PI2BRG	PI1CON 31:16 71500 31:16 71500 31:16 7118UF 31:16 7118UF 31:16 7118UF 31:16 712CON 31:16 712CON 31:16 712CON 31:16 712CON 31:16 712STAT 31:16 712BUF 31:16	Image: symbol with	Image: symbol with	Image: second	Image: symbol with sympol with	Image: second	Image: second	$ \begin{array}{ c c c c c c c c c c c c c c c c c c c$	Image: second	Image: constraint of the state of	$ \begin{array}{ c c c c c c } \hline$	$ \frac{1}{150} \ 1$	Image: state in the s	Image: style	Image: series of the	1 1	Image: state in the state in therestate in the state in the state in the state in the

Legena: /alue on Reset, = unimplemented, read as 10°. Reset values are shown in hexadecimal.

All registers in this table except SPIxBUF have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See Section 12.1.1 "CLR, SET and INV Registers" for more information. SPI2 Module is not present on PIC32MX420FXXXX/440FXXXX devices. Note 1:

2:

PORTC REGISTERS MAP FOR PIC32MX320F128L, PIC32MX340F128L, PIC32MX360F256L, PIC32MX360F512L, PIC32MX440F128L, PIC32MX460F256L AND PIC32MX460F512L DEVICES ONLY⁽¹⁾ TABLE 4-23:

ess										Bi	ts								
Virtual Address (BF88_#)	Register Name	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
6080	TRISC	31:16	—	—	—	—	—	-	—	—	—	—	—	—	-	—	—	—	0000
6060	TRISC	15:0	TRISC15	TRISC14	TRISC13	TRISC12	—	_	_	—	—	—	—	TRISC4	TRISC3	TRISC2	TRISC1	_	F01E
6090	PORTC	31:16	_	_	_	—	_	_	_	—	_	—	—	—	_	—	—	_	0000
0090	FURIC	15:0	RC15	RC14	RC13	RC12	—	—	—	—	—	_	—	RC4	RC3	RC2	RC1	_	xxxx
60A0	LATC	31:16	-	—	—	—	—	—	—	—	—	_	—	—	—	—	—	_	0000
00A0	LAIC	15:0	LATC15	LATC14	LATC13	LATC12	_	—	-	-	-	-	-	LATC4	LATC3	LATC2	LATC1	-	xxxx
60B0	ODCC	31:16		_	_				_	—	_	_	—	—	_	—	—	_	0000
0000	ODCC	15:0	ODCC15	ODCC14	ODCC13	ODCC12	—	—	—	—	—	_	_	ODCC4	ODCC3	ODCC2	ODCC1	_	0000

.eye

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See Section 12.1.1 "CLR, SET and INV Registers" for more information.

PORTC REGISTERS MAP FOR PIC32MX320F032H, PIC32MX320F064H, PIC32MX320F128H, PIC32MX340F128H, TABLE 4-24: PIC32MX340F256H, PIC32MX340F512H, PIC32MX420F032H, PIC32MX440F128H, PIC32MX440F256H AND PIC32MX440F512H DEVICES ONLY⁽¹⁾

ess										Bi	ts								
Virtual Address (BF88_#)	Register Name	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
6080	TRISC	31:16	—		—	—		-	_			—	—	—	—	—	—	—	0000
6060	IRISC	15:0	TRISC15	TRISC14	TRISC13	TRISC12	—	—	_	—		_	—	—	_	—	—	_	F000
6090	PORTC	31:16	-	—	—	—	-	_	—	_	—	—	_	—	—	—	—	—	0000
6090	PURIC	15:0	RC15	RC14	RC13	RC12	—	—	_	—		—	_	_	_	—	—	_	xxxx
60A0	LATC	31:16	-	—	—	—	-	_	—	_	—	—	_	—	—	—	—	—	0000
OUAU	LAIC	15:0	LATC15	LATC14	LATC13	LATC12	-	_	—	_	—	—	_	—	—	—	—	—	xxxx
CORO	ODCC	31:16	—		—	—	_	—	_	_		-	_			—	—	_	0000
60B0	ODUU	15:0	ODCC15	ODCC14	ODCC13	ODCC12	_	_		_	_					_	—		0000
Legend	1: x =	unknov	vn value on l	Reset. — = I	unimplement	ted, read as '	0'. Reset va	lues are sho	wn in hexad	ecimal.									-

Legend

All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See Section 12.1.1 "CLR, SET and INV Registers" for more Note 1: information.

TABLE 4-29: PORTF REGISTERS MAP FOR PIC32MX320F128L, PIC32MX340F128L, PIC32MX360F256L AND PIC32MX360F512L DEVICES ONLY⁽¹⁾

ess										Bi	ts								
Virtual Address (BF88_#)	Register Name	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
6140	TRISF	31:16	_		-		_	—	_	-	—	_	—	-	—	-	—	—	0000
0140	TRISE	15:0	-	_	TRISF13	TRISF12	-	_	_	TRISF8	TRISF7	TRISF6	TRISF5	TRISF4	TRISF3	TRISF2	TRISF1	TRISF0	31FF
6150	PORTF	31:16	-	_	-	—	-	_	-	-	_	-	_	-	_	-	_	-	0000
0150	FURIF	15:0	-	—	RF13	RF12	-	—	—	RF8	RF7	RF6	RF5	RF4	RF3	RF2	RF1	RF0	xxxx
6160	LATF	31:16		—	-	—		-			-		-		-	-	-		0000
0100	LAIF	15:0	-	_	LATF13	LATF12	-	_	—	LATF8	LATF7	LATF6	LATF5	LATF4	LATF3	LATF2	LATF1	LATF0	xxxx
6170	ODCF	31:16	_			—	_	_			_		_		_	-	_	_	0000
0170		15:0	_	—	ODCF13	ODCF12	_	_		ODCF8	ODCF7	ODCF6	ODCF5	ODCF4	ODCF3	ODCF2	ODCF1	ODCF0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See Section 12.1.1 "CLR, SET and INV Registers" for more information.

TABLE 4-30: PORTF REGISTERS MAP FOR PIC32MX440F128L, PIC32MX460F256L AND PIC32MX460F512L DEVICES ONLY⁽¹⁾

ess										Bi	ts								
Virtual Address (BF88_#)	Register Name	Bit Range	31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
6140	TRISF	31:16	-	—	—	—	—	—	—	-	—	—	—	—	—	-	—	—	0000
0140	INISE	15:0	-	—	TRISF13	TRISF12	_	—	—	TRISF8		—	TRISF5	TRISF4	TRISF3	TRISF2	TRISF1	TRISF0	313F
6150	PORTF	31:16		_	_	—	_	_	_	_		_	—	—	_	—	—	—	0000
0150	FURIF	15:0		-	RF13	RF12	_	-	-	RF8		-	RF5	RF4	RF3	RF2	RF1	RF0	xxxx
6160	LATF	31:16	-	—	_	—	_	—	—	—		—	—	—	—	—	—	—	0000
0100	LAII	15:0			LATF13	LATF12	-	-	-	LATF8		-	LATF5	LATF4	LATF3	LATF2	LATF1	LATF0	xxxx
6170	ODCF	31:16	_		_	—	_		-	—	_	-	—			—	—	_	0000
0170		15:0	-	_	ODCF13	ODCF12	_			ODCF8	-		ODCF5	ODCF4	ODCF3	ODCF2	ODCF1	ODCF0	0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See Section 12.1.1 "CLR, SET and INV Registers" for more information.

NOTES:

Interrupt Source ⁽¹⁾	IRQ	Vector Number		Interrup	t Bit Location	
Highest Natural Order F	Priority		Flag	Enable	Priority	Subpriority
SPI2E – SPI2 Fault	37	31	IFS1<5>	IEC1<5>	IPC7<28:26>	IPC7<25:24>
SPI2TX – SPI2 Transfer Done	38	31	IFS1<6>	IEC1<6>	IPC7<28:26>	IPC7<25:24>
SPI2RX – SPI2 Receive Done	39	31	IFS1<7>	IEC1<7>	IPC7<28:26>	IPC7<25:24>
U2E – UART2 Error	40	32	IFS1<8>	IEC1<8>	IPC8<4:2>	IPC8<1:0>
U2RX – UART2 Receiver	41	32	IFS1<9>	IEC1<9>	IPC8<4:2>	IPC8<1:0>
U2TX – UART2 Transmitter	42	32	IFS1<10>	IEC1<10>	IPC8<4:2>	IPC8<1:0>
I2C2B – I2C2 Bus Collision Event	43	33	IFS1<11>	IEC1<11>	IPC8<12:10>	IPC8<9:8>
I2C2S – I2C2 Slave Event	44	33	IFS1<12>	IEC1<12>	IPC8<12:10>	IPC8<9:8>
I2C2M – I2C2 Master Event	45	33	IFS1<13>	IEC1<13>	IPC8<12:10>	IPC8<9:8>
FSCM – Fail-Safe Clock Monitor	46	34	IFS1<14>	IEC1<14>	IPC8<20:18>	IPC8<17:16>
RTCC – Real-Time Clock and Calendar	47	35	IFS1<15>	IEC1<15>	IPC8<28:26>	IPC8<25:24>
DMA0 – DMA Channel 0	48	36	IFS1<16>	IEC1<16>	IPC9<4:2>	IPC9<1:0>
DMA1 – DMA Channel 1	49	37	IFS1<17>	IEC1<17>	IPC9<12:10>	IPC9<9:8>
DMA2 – DMA Channel 2	50	38	IFS1<18>	IEC1<18>	IPC9<20:18>	IPC9<17:16>
DMA3 – DMA Channel 3	51	39	IFS1<19>	IEC1<19>	IPC9<28:26>	IPC9<25:24>
FCE – Flash Control Event	56	44	IFS1<24>	IEC1<24>	IPC11<4:2>	IPC11<1:0>
USB	57	45	IFS1<25>	IEC1<25>	IPC11<12:10>	IPC11<9:8>
		Lowest Na	tural Order Pri	ority	•	

TABLE 7-1: INTERRUPT IRQ AND VECTOR LOCATION (CONTINUED)

Note 1: Not all interrupt sources are available on all devices. See TABLE 1: "PIC32MX General Purpose – Features" and TABLE 2: "PIC32MX USB – Features" for available peripherals.

NOTES:

11.0 USB ON-THE-GO (OTG)

- Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to Section 27. "USB On-The-Go (OTG)" (DS61126) of the "PIC32 Family Reference Manual", which is available from the Microchip web site (www.microchip.com/PIC32).
 - 2: Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The Universal Serial Bus (USB) module contains analog and digital components to provide a USB 2.0 fullspeed and low-speed embedded host, full-speed device, or OTG implementation with a minimum of external components. This module in Host mode is intended for use as an embedded host and therefore does not implement a UHCI or OHCI controller.

The USB module consists of the clock generator, the USB voltage comparators, the transceiver, the Serial Interface Engine (SIE), a dedicated USB DMA controller, pull-up and pull-down resistors, and the register interface. A block diagram of the PIC32MX USB OTG module is presented in Figure 11-1.

The clock generator provides the 48 MHz clock required for USB full-speed and low-speed communication. The voltage comparators monitor the voltage on the VBUS pin to determine the state of the bus. The transceiver provides the analog translation between the USB bus and the digital logic. The SIE is a state machine that transfers data to and from the endpoint buffers, and generates the hardware protocol for data transfers. The USB DMA controller transfers data between the data buffers in RAM and the SIE. The integrated pull-up and pull-down resistors eliminate the need for external signaling components. The register interface allows the CPU to configure and communicate with the module. The PIC32MX USB module includes the following features:

- USB Full-Speed Support for Host and Device
- Low-Speed Host Support
- USB OTG Support
- Integrated Signaling Resistors
- Integrated Analog Comparators for VBUS Monitoring
- Integrated USB Transceiver
- Transaction Handshaking Performed by Hardware
- Endpoint Buffering Anywhere in System RAM
- Integrated DMA to Access System RAM and Flash

Note: The implementation and use of the USB specifications, as well as other third-party specifications or technologies, may require licensing; including, but not limited to, USB Implementers Forum, Inc. (also referred to as USB-IF). The user is fully responsible for investigating and satisfying any applicable licensing obligations.

12.1 Parallel I/O (PIO) Ports

All port pins have three registers (TRIS, LAT and PORT) that are directly associated with their operation.

TRIS is a data direction or tri-state control register that determines whether a digital pin is an input or an output. Setting a TRISx register bit = 1 configures the corresponding I/O pin as an input; setting a TRISx register bit = 0 configures the corresponding I/O pin as an output. All port I/O pins are defined as inputs after a device Reset. Certain I/O pins are shared with analog peripherals and default to analog inputs after a device Reset.

PORT is a register used to read the current state of the signal applied to the port I/O pins. Writing to a PORTx register performs a write to the port's latch, LATx register, latching the data to the port's I/O pins.

LAT is a register used to write data to the port I/O pins. The LATx latch register holds the data written to either the LATx or PORTx registers. Reading the LATx latch register reads the last value written to the corresponding port or latch register.

Not all port I/O pins are implemented on some devices, therefore, the corresponding PORTx, LATx and TRISx register bits will read as zeros.

12.1.1 CLR, SET AND INV REGISTERS

Every I/O module register has a corresponding CLR (clear), SET (set) and INV (invert) register designed to provide fast atomic bit manipulations. As the name of the register implies, a value written to a SET, CLR or INV register effectively performs the implied operation, but only on the corresponding base register and only bits specified as '1' are modified. Bits specified as '0' are not modified.

Reading SET, CLR and INV registers returns undefined values. To see the affects of a write operation to a SET, CLR or INV register, the base register must be read.

Note:	Using a PORTxINV register to toggle a bit is recommended because the operation is
	performed in hardware atomically, using
	fewer instructions as compared to the tra-
	ditional read-modify-write method shown
	below:

PORTC ^= 0x0001;

12.1.2 DIGITAL INPUTS

Pins are configured as digital inputs by setting the corresponding TRIS register bits = 1. When configured as inputs, they are either TTL buffers or Schmitt Triggers. Several digital pins share functionality with analog inputs and default to the analog inputs at POR. Setting the corresponding bit in the AD1PCFG register = 1 enables the pin as a digital pin.

The maximum input voltage allowed on the input pins is the same as the maximum VIH specification. Refer to **Section 29.0 "Electrical Characteristics"** for VIH specification details.

Note:	Analog levels on any pin that is defined as
	a digital input (including the ANx pins)
	may cause the input buffer to consume
	current that exceeds the device specifica-
	tions.

12.1.3 ANALOG INPUTS

Certain pins can be configured as analog inputs used by the ADC and Comparator modules. Setting the corresponding bits in the AD1PCFG register = 0 enables the pin as an analog input pin and must have the corresponding TRIS bit set = 1 (input). If the TRIS bit is cleared = 0 (output), the digital output level (VOH or VOL) will be converted. Any time a port I/O pin is configured as analog, its digital input is disabled and the corresponding PORTx register bit will read '0'. The AD1PCFG Register has a default value of 0x0000; therefore, all pins that share ANx functions are analog (not digital) by default.

12.1.4 DIGITAL OUTPUTS

Pins are configured as digital outputs by setting the corresponding TRIS register bits = 0. When configured as digital outputs, these pins are CMOS drivers or can be configured as open drain outputs by setting the corresponding bits in the ODCx Open-Drain Configuration register.

The open-drain feature allows the generation of outputs higher than VDD (e.g., 5V) on any desired 5V tolerant pins by using external pull-up resistors. The maximum open-drain voltage allowed is the same as the maximum VIH specification.

See the **"Pin Diagrams"** section for the available pins and their functionality.

12.1.5 ANALOG OUTPUTS

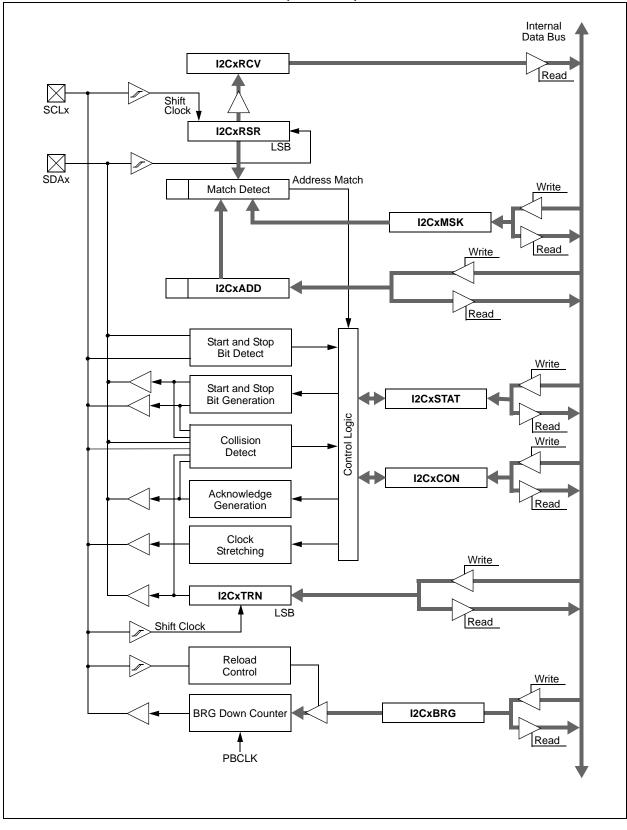
Certain pins can be configured as analog outputs, such as the CVREF output voltage used by the comparator module. Configuring the Comparator Reference module to provide this output will present the analog output voltage on the pin, independent of the TRIS register setting for the corresponding pin.

12.1.6 INPUT CHANGE NOTIFICATION

The input change notification function of the I/O ports (CNx) allows devices to generate interrupt requests in response to change of state on selected pin.

Each CNx pin also has a weak pull-up, which acts as a current source connected to the pin. The pull-ups are enabled by setting corresponding bit in CNPUE register.

FIGURE 18-1: I^2C^{TM} BLOCK DIAGRAM (x = 1 OR 2)



23.0 COMPARATOR

- Note 1: This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. Refer to Section 19. "Comparator" (DS61110) of the "PIC32 Family Reference Manual", which is available from the Microchip web site (www.microchip.com/PIC32).
 - 2: Some registers and associated bits described in this section may not be available on all devices. Refer to Section 4.0 "Memory Organization" in this data sheet for device-specific register and bit information.

The PIC32MX3XX/4XX Analog Comparator module contains one or more comparator(s) that can be configured in a variety of ways.

Following are some of the key features of this module:

- · Selectable inputs available include:
 - Analog inputs multiplexed with I/O pins
 - On-chip internal absolute voltage reference (IVREF)
 - Comparator voltage reference (CVREF)
- · Outputs can be inverted
- · Selectable interrupt generation

A block diagram of the comparator module is illustrated in Figure 23-1.

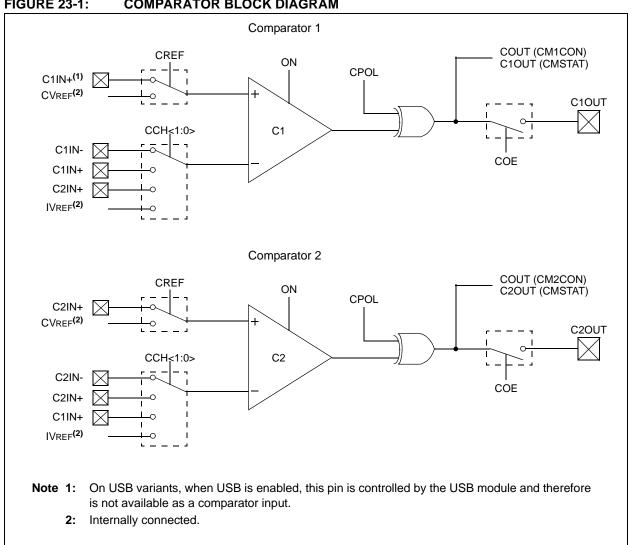


FIGURE 23-1: **COMPARATOR BLOCK DIAGRAM**

28.11 PICkit 2 Development Programmer/Debugger and PICkit 2 Debug Express

The PICkit[™] 2 Development Programmer/Debugger is a low-cost development tool with an easy to use interface for programming and debugging Microchip's Flash families of microcontrollers. The full featured Windows[®] programming interface supports baseline (PIC10F, PIC12F5xx, PIC16F5xx), midrange (PIC12F6xx, PIC16F), PIC18F, PIC24, dsPIC30, dsPIC33, and PIC32 families of 8-bit, 16-bit, and 32-bit microcontrollers, and many Microchip Serial EEPROM products. With Microchip's powerful MPLAB Integrated Development Environment (IDE) the PICkit[™] 2 enables in-circuit debugging on most PIC® microcontrollers. In-Circuit-Debugging runs, halts and single steps the program while the PIC microcontroller is embedded in the application. When halted at a breakpoint, the file registers can be examined and modified.

The PICkit 2 Debug Express include the PICkit 2, demo board and microcontroller, hookup cables and CDROM with user's guide, lessons, tutorial, compiler and MPLAB IDE software.

28.12 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at VDDMIN and VDDMAX for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages and a modular, detachable socket assembly to support various package types. The ICSP™ cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices and incorporates an MMC card for file storage and data applications.

28.13 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM[™] and dsPICDEM[™] demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ[®] security ICs, CAN, IrDA[®], PowerSmart battery management, SEEVAL[®] evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

29.1 DC Characteristics

TABLE 29-1: OPERATING MIPS VS. VOLTAGE

Characteristic	VDD Range	Temp. Range	Max. Frequency
Characteristic	(in Volts)	(in °C)	PIC32MX3XX/4XX
DC5	2.3V-3.6V	-40°C to +85°C	80 MHz (Note 1)
DC5b	2.3V-3.6V	-40°C to +105°C	80 MHz (Note 1)

Note 1: 40 MHz maximum for PIC32MX320F032H and PIC32MX420F032H devices.

TABLE 29-2: THERMAL OPERATING CONDITIONS

Rating	Symbol	Min.	Typical	Max.	Unit
Industrial Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+125	°C
Operating Ambient Temperature Range	TA	-40	—	+85	°C
V-Temp Temperature Devices					
Operating Junction Temperature Range	TJ	-40	—	+140	°C
Operating Ambient Temperature Range	TA	-40	—	+105	°C
Power Dissipation: Internal Chip Power Dissipation: PINT = VDD x (IDD - S IOH)		PINT + PI/O		W	
I/O Pin Power Dissipation: I/O = S ({VDD - VOH} x IOH) + S (VOL x IOL))					
Maximum Allowed Power Dissipation	PDMAX	(TJ — TA)/θJ	IA	W

TABLE 29-3: THERMAL PACKAGING CHARACTERISTICS

Characteristics	Symbol	Typical	Max.	Unit	Notes
Package Thermal Resistance, 121-Pin XBGA (10x10x1.1 mm)	θја	40	_	°C/W	1
Package Thermal Resistance, 100-Pin TQFP (12x12x1 mm)	θја	43	_	°C/W	1
Package Thermal Resistance, 64-Pin TQFP (10x10x1 mm)	θja	47	_	°C/W	1
Package Thermal Resistance, 64-Pin QFN (9x9x0.9 mm)	θja	28	_	°C/W	1

Note 1: Junction to ambient thermal resistance, Theta-JA (θ JA) numbers are achieved by package simulations.

TABLE 29-4: DC TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	Symbol	Characteristics	Min. Typical Max. Units Condi				
Operati	ng Voltag	e					
DC10	Vdd	Supply Voltage	2.3	—	3.6	V	—
DC12	Vdr	RAM Data Retention Voltage (Note 1)	1.75	—		V	_
DC16	VPOR	VDD Start Voltage to Ensure Internal Power-on Reset Signal	1.75	_	1.95	V	_
DC17	SVDD	VDD Rise Rate to Ensure Internal Power-on Reset Signal	0.05	—	_	V/ms	_

Note 1: This is the limit to which VDD can be lowered without losing RAM data.

DC CHARACTERISTICS				ard Operati s otherwise ting tempera	e statec ature	l) -40°C ≤	: 2.3V to 3.6V TA ≤+85°C for Industrial TA ≤+105°C for V-Temp
Param. No.	Symbol	Characteristics	Min. Typical ⁽¹⁾ Max. Units Conditions				
		Program Flash Memory					
D130	Eр	Cell Endurance	1000	—	_	E/W	—
D131	Vpr	VDD for Read	Vmin	—	3.6	V	—
D132	VPEW	VDD for Erase or Write	3.0	—	3.6	V	—
D134	TRETD	Characteristic Retention	20	—	_	Year	—
D135	IDDP	Supply Current during Programming	—	10	—	mA	—
	Tww	Word Write Cycle Time	20	—	40	μs	—
D136	Trw	Row Write Cycle Time ⁽²⁾ (128 words per row)	3	4.5	—	ms	_
D137	TPE	Page Erase Cycle Time	20	—	—	ms	—
	TCE	Chip Erase Cycle Time	80	—	—	ms	—
D138	LVDstartup	Flash LVD Delay	_	—	6	μs	

TABLE 29-11: DC CHARACTERISTICS: PROGRAM MEMORY⁽³⁾

Note 1: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated.

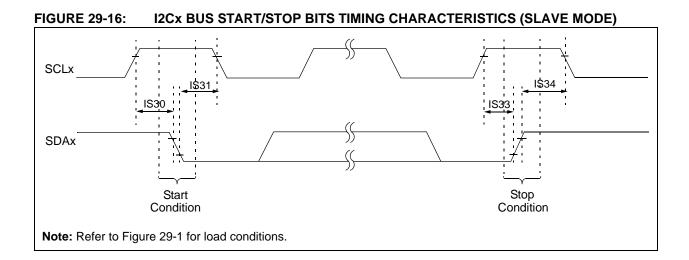
2: The minimum SYSCLK for row programming is 4 MHz. Care should be taken to minimize bus activities during row programming, such as suspending any memory-to-memory DMA operations. If heavy bus loads are expected, selecting Bus Matrix Arbitration mode 2 (rotating priority) may be necessary. The default Arbitration mode is mode 1 (CPU has lowest priority).

3: Refer to the "*PIC32MX Flash Programming Specification*" (DS61145) for operating conditions during programming and erase cycles.

TABLE 29-12: PROGRAM FLASH MEMORY WAIT STATE CHARACTERISTICS

DC CHARACTERISTICS	Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp			
Required Flash wait states	SYSCLK	Units	Comments	
0 Wait State	0 to 30			
1 Wait State	31 to 60	MHz	—	
2 Wait States	61 to 80			

Note 1: 40 MHz maximum for PIC32MX320F032H and PIC32MX420F032H devices.





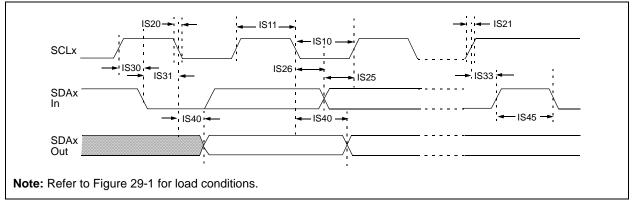


TABLE 29-40: OTG ELECTRICAL SPECIFICATIONS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial -40°C ≤TA ≤+105°C for V-Temp				≤+85°C for Industrial
Param. No.	Symbol	Characteristics ⁽¹⁾	Min. Typ Max. Units Cond				Conditions
USB313	VUSB	USB Voltage	3.0		3.6	V	Voltage on VUSB must be in this range for proper USB operation.
USB315	VILUSB	Input Low Voltage for USB Buffer	—	_	0.8	V	—
USB316	VIHUSB	Input High Voltage for USB Buffer	2.0	—	_	V	—
USB318	VDIFS	Differential Input Sensitivity	—		0.2	V	The difference between D+ and D- must exceed this value while VCM is met.
USB319	VCM	Differential Common Mode Range	0.8	_	2.5	V	—
USB320	Ζουτ	Driver Output Impedance	28.0	—	44.0	Ω	—
USB321	Vol	Voltage Output Low	0.0	_	0.3	V	1.5 k Ω load connected to 3.6V.
USB322	Voн	Voltage Output High	2.8	—	3.6	V	1.5 k Ω load connected to ground.

Note 1: These parameters are characterized, but not tested in manufacturing.

64-Lead Plastic Quad Flat, No Lead Package (MR) – 9x9x0.9 mm Body [QFN] With 7.15 x 7.15 Exposed Pad [QFN]

For the most current package drawings, please see the Microchip Packaging Specification located at Note: http://www.microchip.com/packaging



	Units	١	MILLIMETER	S
Dimens	Dimension Limits			MAX
Number of Pins	64			
Pitch	е	0.50 BSC		
Overall Height	A	0.80	0.90	1.00
Standoff	A1	0.00	0.02	0.05
Contact Thickness	A3	0.20 REF		
Overall Width	E	9.00 BSC		
Exposed Pad Width	E2	7.05	7.15	7.50
Overall Length	D	9.00 BSC		
Exposed Pad Length	D2	7.05	7.15	7.50
Contact Width	b	0.18	0.25	0.30
Contact Length	L	0.30	0.40	0.50
Contact-to-Exposed Pad	K	0.20	-	-

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. Package is saw singulated.

3. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-149C Sheet 2 of 2

Product Identification System

To order or obtain informat	tion, e.g., on pricing or delivery, refer to the factory or the li	isted sales office.				
Microchip Brand Architecture Product Groups Flash Memory Family Program Memory Size Pin Count Tape and Reel Flag (if Speed Temperature Range Package	PIC32 MX 3XX F 512 H T - 80 I / PT - XXX	Examples: PIC32MX320F032H-40I/PT: General purpose PIC32MX, 32 KB program memory, 64-pin, Industrial temperature, TQFP package. PIC32MX360F256L-80I/PT: General purpose PIC32MX, 256 KB program memory, 100-pin, Industrial temperature, TQFP package.				
Flash Memory Family						
Architecture	MX = 32-bit RISC MCU core					
Product Groups	3XX = General purpose microcontroller family 4XX = USB					
Flash Memory Family	F = Flash program memory					
Program Memory Size	32 = 32K 64 = 64K 128 = 128K 256 = 256K 512 = 512K					
Speed	40 = 40 MHz 80 = 80 MHz					
Pin Count	H = 64-pin L = 100-pin					
Temperature Range	I = -40° C to $+85^{\circ}$ C (Industrial) V = -40° C to $+105^{\circ}$ C (V-Temp)					
Package	PT = 64-Lead (10x10x1 mm) TQFP (Thin Quad Flatpack) PT = 100-Lead (12x12x1 mm) TQFP (Thin Quad Flatpack) MR = 64-Lead (9x9x0.9 mm) QFN (Plastic Quad Flat) BG = 121-Lead (10x10x1.1 mm) XBGA (Plastic Thin Profile Ball Grid Array)					
Pattern	Three-digit QTP, SQTP, Code or Special Requirements (blank otherwise) ES = Engineering Sample					